



60V N-Channel Enhancement Mode MOSFET - ESD Protected

Voltage

60 V

Current

300mA

Features

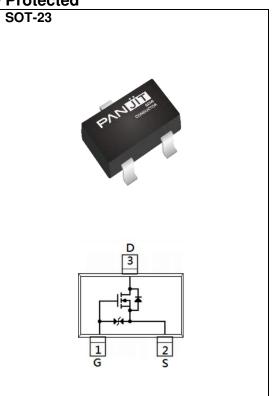
- $R_{DS(ON)}$, $V_{GS}@10V$, $I_D@500mA<3\Omega$
- $R_{DS(ON)}$, $V_{GS}@4.5V$, $I_{D}@200mA<4\Omega$
- Advanced Trench Process Technology
- High Density Cell Design For Ultra Low On-Resistance
- Very Low Leakage Current In Off Condition
- Specially Designed for Battery Operated Systems, Solid-State Relays Drivers: Relay, Displays, Memories, etc
- ESD Protected 2KV HBM
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: SOT-23 Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0084 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	<u>+</u> 20		
Continuous Drain Current(Note 4)		I _D	300	mA	
Pulsed Drain Current ^(Note 1)		I _{DM}	2000		
Power Dissipation	T _A =25°C	P_{D}	500	mW	
	Derate above 25°C		4	mW/°C	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~150	°C	
Typical Thermal Resistance - Junction to Ambient ^(Note 3,4)		Reja	250	°C/W	





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =10uA	60	-	-	V
Gate Threshold Voltage	$V_{\text{GS(th)}}$	V _{DS} =V _{GS} , I _D =250uA	1	-	2.5	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V,I _D =500mA	-	-	3	Ω
		V _{GS} =4.5V,I _D =200mA	-	-	4	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	uA
Gate-Source Leakage Current	Igss	V _{GS=±20V} ,V _{DS} =0V	-	-	<u>+</u> 10	
Forward Transconductance	g fs	V_{DS} =15V, I_D =250mA	100	-	-	mS
Dynamic ^(Note 5)						
Total Gate Charge	Q_g	V _{DS} =15V, I _D =250mA, V _{GS} =5V ^(Note 1,2)	-	0.8	-	nC
Gate-Source Charge	Qgs		-	0.35	-	
Gate-Drain Charge	Q_{gd}		-	0.2	-	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHZ	-	35	-	pF
Output Capacitance	Coss		-	13	-	
Reverse Transfer Capacitance	Crss		-	8	-	
Turn-On Delay Time	td _(on)	\/ 20\/ 200 _m A	-	2.7	-	
Turn-On Rise Time	tr	$\begin{array}{l} V_{DD}{=}30V,\ I_{D}{=}200mA,\\ V_{GS}{=}10V,\\ R_{G}{=}10\Omega^{(Note\ 1,2)} \end{array}$	-	19	-	ns
Turn-Off Delay Time	td _(off)		-	15	-	
Turn-Off Fall Time	tf		-	23	-	
Drain-Source Diode						
Maximum Continuous Drain-Source			-	-	300	mA
Diode Forward Current	ls					
Diode Forward Voltage	V _{SD}	I _S =200mA, V _{GS} =0V	-	0.82	1.3	V

NOTES:

- 1. Pulse width < 300us, Duty cycle < 2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Rejah is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.
- 4. The maximum current rating is package limited.
- 5. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

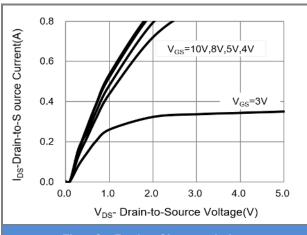


Fig.1 On-Region Characteristics

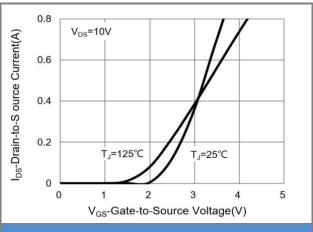


Fig.2 Transfer Characteristics

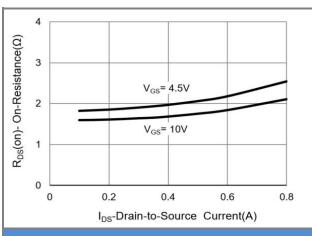


Fig.3 On-Resistance vs. Drain Current

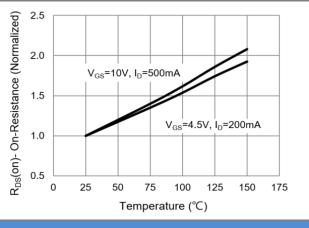
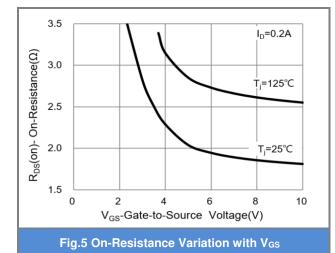
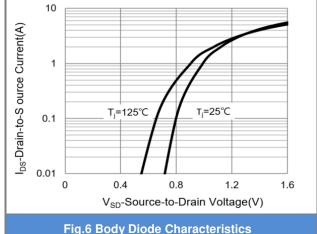


Fig.4 On-Resistance vs. Junction temperature









TYPICAL CHARACTERISTIC CURVES

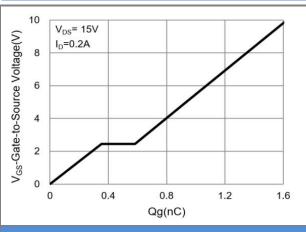


Fig.7 Gate-Charge Characteristics

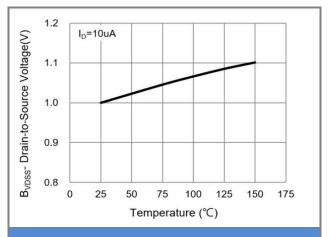


Fig.8 Breakdown Voltage Variation vs. Temperature

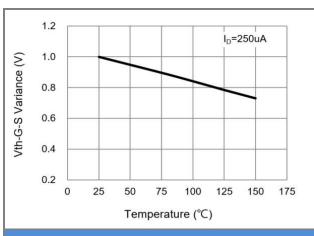


Fig.9 Threshold Voltage Variation with Temperature

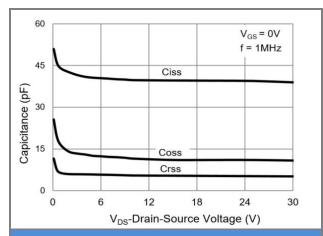


Fig.10 Capacitance vs. Drain-Source Voltage

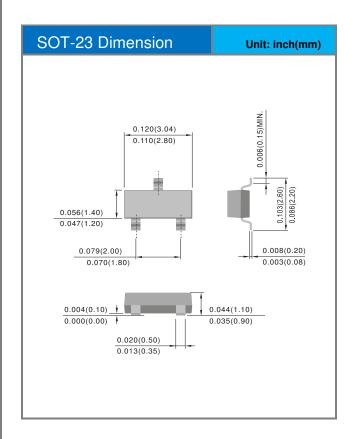


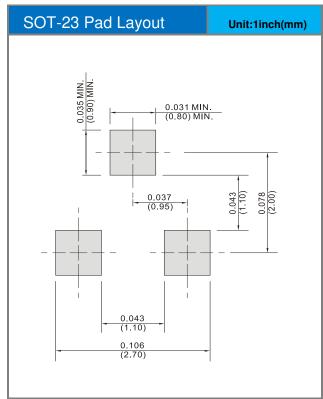


Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
2N7002K_R1_00501	SOT-23	3K pcs / 7" reel	K72	Halogen free RoHS compliant

Packaging Information & Mounting Pad Layout









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